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48-Lane 12-Port PCIe® Gen2 System Interconnect Switch

89HPES48T12G2
Data Sheet

Device Overview

The 89HPES48T12G2 is a member of the IDT PRECISE™ family of PCI Express® switching solutions. The PES48T12G2 is a 48-lane, 12-port system interconnect switch optimized for PCI Express Gen2 packet switching in high-performance applications, supporting multiple simultaneous peer-to-peer traffic flows. Target applications include servers, storage, communications, embedded systems, and multi-host or intelligent I/O based systems with inter-domain communication.

Features

- **High Performance Non-Blocking Switch Architecture**
  - 48-lane 12-port PCIe switch
    - *Six x8 ports switch ports each of which can bifurcate to two x4 ports (total of twelve x4 ports)*
  - Integrated SerDes supports 5.0 GT/s Gen2 and 2.5 GT/s Gen1 operation
  - Delivers up to *48 GBps (384 Gbps)* of switching capacity
  - Supports 128 Bytes to 2 KB maximum payload size
  - Low latency cut-through architecture
  - Supports one virtual channel and eight traffic classes
- **Standards and Compatibility**
  - PCI Express Base Specification 2.0 compliant
  - Implements the following optional PCI Express features
    - *Advanced Error Reporting (AER) on all ports*
    - *End-to-End CRC (ECRC)*
    - *Access Control Services (ACS)*
    - *Power Budgeting Enhanced Capability*
    - *Device Serial Number Enhanced Capability*
    - *Sub-System ID and Sub-System Vendor ID Capability*
    - *Internal Error Reporting ECN*
    - *Multicast ECN*
    - *VGA and ISA enable*
    - *L0s and L1 ASPM*
    - *ARI ECN*
- **Port Configurability**
  - x4 and x8 ports
    - *Ability to merge adjacent x4 ports to create a x8 port*
  - Automatic per port link width negotiation (x8 → x4 → x2 → x1)
  - Crosslink support
  - Automatic lane reversal
  - Autonomous and software managed link width and speed control
  - Per lane SerDes configuration
    - *De-emphasis*
    - *Receive equalization*
    - *Drive strength*
- **Initialization / Configuration**
  - Supports Root (BIOS, OS, or driver), Serial EEPROM, or SMBus switch initialization
  - Common switch configurations are supported with pin strapping (no external components)
  - Supports in-system Serial EEPROM initialization/programming
- **Quality of Service (QoS)**
  - Port arbitration
    - *Round robin*
    - *Weighted Round Robin (WRR)*
  - Request metering
    - *IDT proprietary feature that balances bandwidth among switch ports for maximum system throughput*
  - High performance switch core architecture
    - *Combined Input Output Queued (CIOQ) switch architecture with large buffers*
- **Multicast**
  - Compliant to the PCI-SIG multicast ECN
  - Supports arbitrary multicasting of Posted transactions
  - Supports 64 multicast groups
  - Multicast overlay mechanism support
  - ECRC regeneration support
- **Clocking**
  - Supports 100 MHz and 125 MHz reference clock frequencies
  - Flexible clocking modes
    - *Common clock*
    - *Non-common clock*
- **Hot-Plug and Hot Swap**
  - Hot-plug controller on all ports
    - *Hot-plug supported on all downstream switch ports*
  - All ports support hot-plug using low-cost external I^2C I/O expanders
  - Configurable presence detect supports card and cable applications
  - GPE output pin for hot-plug event notification
    - *Enables SCI/SMI generation for legacy operating system support*
  - Hot swap capable I/O
- **Power Management**
  - Supports D0, D3hot and D3 power management states

- Active State Power Management (ASPM)
  - *Supports L0, L0s, L1, L2/L3 Ready and L3 link states*
  - *Configurable L0s and L1 entry timers allow performance/ power-savings tuning*
- Supports PCI Express Power Budgeting Capability
- SerDes power savings
  - *Supports low swing / half-swing SerDes operation*
  - *SerDes optionally turned-off in D3hot*
  - *SerDes associated with unused ports are turned-off*
  - *SerDes associated with unused lanes are placed in a low power state*

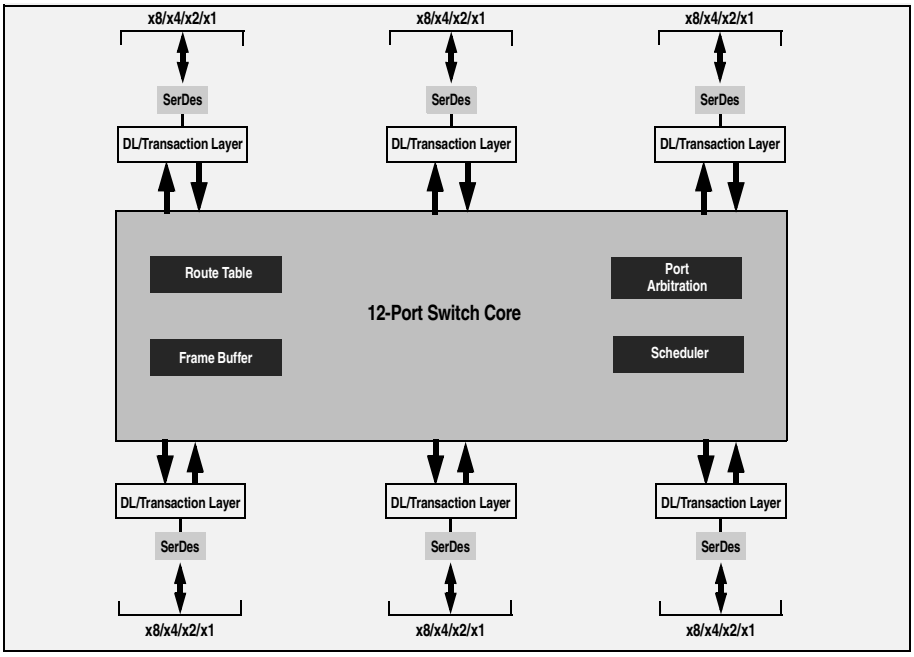
- **9 General Purpose I/O**
- **Reliability, Availability and Serviceability (RAS)**
  - ECRC support
  - AER on all ports
  - SECDED ECC protection on all internal RAMs
  - End-to-end data path parity protection
  - Checksum Serial EEPROM content protected
  - Autonomous link reliability (preserves system operation in the presence of faulty links)
  - Ability to generate an interrupt (INTx or MSI) on link up/down transitions
- **Test and Debug**
  - On-chip link activity and status outputs available for Port 0 (upstream port)
  - Per port link activity and status outputs available using external I^2C I/O expander for all other ports
  - SerDes test modes
  - Supports IEEE 1149.6 AC JTAG and IEEE 1149.1 JTAG
- **Power Supplies**
  - Requires only two power supply voltages (1.0 V and 2.5 V) Note that a 3.3V is preferred for V_{DD}I/O
  - No power sequencing requirements
- **Packaged in a 27mm x 27mm 676-ball Flip Chip BGA with 1mm ball spacing**

Product Description

Utilizing standard PCI Express interconnect, the PES48T12G2 provides the most efficient fan-out solution for applications requiring high throughput, low latency, and simple board layout with a minimum number of board layers. It provides 48 GBps (384 Gbps) of aggregated, full-duplex switching capacity through 48 integrated serial lanes, using proven and robust IDT technology. Each lane provides 5 Gbps of bandwidth in both directions and is fully compliant with PCI Express Base Specification, Revision 2.0.

The PES48T12G2 is based on a flexible and efficient layered architecture. The PCI Express layer consists of SerDes, Physical, Data Link and Transaction layers in compliance with PCI Express Base specification Revision 2.0. The PES48T12G2 can operate either as a store and forward or cut-through switch. It supports eight Traffic Classes (TCs) and one Virtual Channel (VC) with sophisticated resource management to enable efficient switching and I/O connectivity for servers, storage, and embedded processors with limited connectivity.

Block Diagram



48 PCI Express Lanes
Up to 6 x8 ports or 12 x4 Ports

Figure 1 Internal Block Diagram

SMBus Interface

The PES48T12G2 contains an SMBus master interface. This master interface allows the default configuration register values of the PES48T12G2 to be overridden following a reset with values programmed in an external serial EEPROM. The master interface is also used by an external Hot-Plug I/O expander. Two pins make up the SMBus master interface: an SMBus clock pin and an SMBus data pin. Four pins make up the SMBus slave interface: an SMBus clock pin and an SMBus data pin plus two address pins, SSMBADDR[2,1].

As shown in Figure 2, the master and slave SMBuses may only be used in a split configuration.

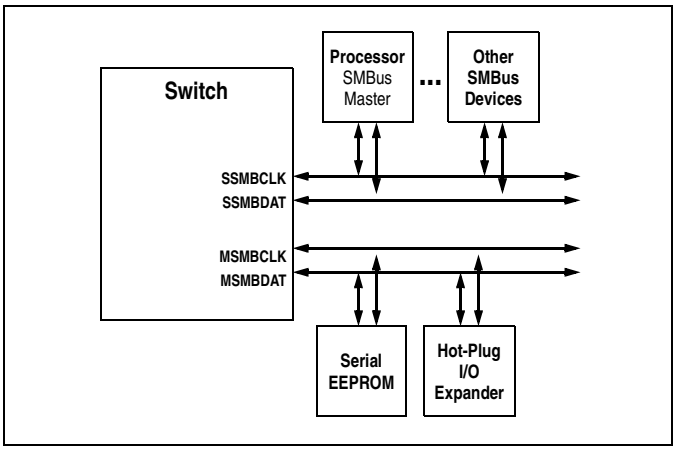


Figure 2 Split SMBus Interface Configuration

The switch's SMBus master interface does not support SMBus arbitration. As a result, the switch's SMBus master must be the only master in the SMBus lines that connect to the serial EEPROM and I/O expander slaves. In the split configuration, the master and slave SMBuses operate as two independent buses; thus, multi-master arbitration is not required.

Hot-Plug Interface

The PES48T12G2 supports PCI Express Hot-Plug on each downstream port. To reduce the number of pins required on the device, the PES48T12G2 utilizes an external I/O expander, such as that used on PC motherboards, connected to the SMBus master interface. Following reset and configuration, whenever the state of a Hot-Plug output needs to be modified, the PES48T12G2 generates an SMBus transaction to the I/O expander with the new value of all of the outputs. Whenever a Hot-Plug input changes, the I/O expander generates an interrupt which is received on the IOEXPINTN input pin (alternate function of GPIO) of the PES48T12G2. In response to an I/O expander interrupt, the PES48T12G2 generates an SMBus transaction to read the state of all of the Hot-Plug inputs from the I/O expander.

General Purpose Input/Output

The PES48T12G2 provides 9 General Purpose Input/Output (GPIO) pins that may be used by the system designer as bit I/O ports. Each GPIO pin may be configured independently as an input or output through software control. Some GPIO pins are shared with other on-chip functions. These alternate functions may be enabled via software, SMBus slave interface, or serial configuration EEPROM.

Pin Description

The following tables list the functions of the pins provided on the PES48T12G2. Some of the functions listed may be multiplexed onto the same pin. The active polarity of a signal is defined using a suffix. Signals ending with an “N” are defined as being active, or asserted, when at a logic zero (low) level. All other signals (including clocks, buses, and select lines) will be interpreted as being active, or asserted, when at a logic one (high) level.

Signal	Type	Name/Description
PE00RP[3:0] PE00RN[3:0]	I	**PCI Express Port 0 Serial Data Receive.** Differential PCI Express receive pairs for port 0.
PE00TP[3:0] PE00TN[3:0]	O	**PCI Express Port 0 Serial Data Transmit.** Differential PCI Express transmit pairs for port 0.
PE01RP[3:0] PE01RN[3:0]	I	**PCI Express Port 1 Serial Data Receive.** Differential PCI Express receive pairs for port 1. When port 0 is merged with port 1, these signals become port 0 receive pairs for lanes 4 through 7.
PE01TP[3:0] PE01TN[3:0]	O	**PCI Express Port 1 Serial Data Transmit.** Differential PCI Express transmit pairs for port 1. When port 0 is merged with port 1, these signals become port 0 transmit pairs for lanes 4 through 7.
PE02RP[3:0] PE02RN[3:0]	I	**PCI Express Port 2 Serial Data Receive.** Differential PCI Express receive pairs for port 2.
PE02TP[3:0] PE02TN[3:0]	O	**PCI Express Port 2 Serial Data Transmit.** Differential PCI Express transmit pairs for port 2.
PE03RP[3:0] PE03RN[3:0]	I	**PCI Express Port 3 Serial Data Receive.** Differential PCI Express receive pairs for port 3. When port 2 is merged with port 3, these signals become port 2 receive pairs for lanes 4 through 7.
PE03TP[3:0] PE03TN[3:0]	O	**PCI Express Port 3 Serial Data Transmit.** Differential PCI Express transmit pairs for port 3. When port 2 is merged with port 3, these signals become port 2 transmit pairs for lanes 4 through 7.
PE04RP[3:0] PE04RN[3:0]	I	**PCI Express Port 4 Serial Data Receive.** Differential PCI Express receive pairs for port 4.
PE04TP[3:0] PE04TN[3:0]	O	**PCI Express Port 4 Serial Data Transmit.** Differential PCI Express transmit pairs for port 4.
PE05RP[3:0] PE05RN[3:0]	I	**PCI Express Port 5 Serial Data Receive.** Differential PCI Express receive pairs for port 5. When port 4 is merged with port 5, these signals become port 4 receive pairs for lanes 4 through 7.

Table 1 PCI Express Interface Pins (Part 1 of 2)

Signal	Type	Name/Description
PE05TP[3:0] PE05TN[3:0]	O	**PCI Express Port 5 Serial Data Transmit.** Differential PCI Express transmit pairs for port 5. When port 4 is merged with port 5, these signals become port 4 transmit pairs for lanes 4 through 7.
PE06RP[3:0] PE06RN[3:0]	I	**PCI Express Port 6 Serial Data Receive.** Differential PCI Express receive pairs for port 6.
PE06TP[3:0] PE06TN[3:0]	O	**PCI Express Port 6 Serial Data Transmit.** Differential PCI Express transmit pairs for port 6.
PE07RP[3:0] PE07RN[3:0]	I	**PCI Express Port 7 Serial Data Receive.** Differential PCI Express receive pairs for port 7. When port 6 is merged with port 7, these signals become port 6 receive pairs for lanes 4 through 7.
PE07TP[3:0] PE07TN[3:0]	O	**PCI Express Port 7 Serial Data Transmit.** Differential PCI Express transmit pairs for port 7. When port 6 is merged with port 7, these signals become port 6 transmit pairs for lanes 4 through 7.
PE08RP[3:0] PE08RN[3:0]	I	**PCI Express Port 8 Serial Data Receive.** Differential PCI Express receive pairs for port 8.
PE08TP[3:0] PE08TN[3:0]	O	**PCI Express Port 8 Serial Data Transmit.** Differential PCI Express transmit pairs for port 8.
PE09RP[3:0] PE09RN[3:0]	I	**PCI Express Port 9 Serial Data Receive.** Differential PCI Express receive pairs for port 9. When port 8 is merged with port 9, these signals become port 8 receive pairs for lanes 4 through 7.
PE09TP[3:0] PE09TN[3:0]	O	**PCI Express Port 9 Serial Data Transmit.** Differential PCI Express transmit pairs for port 9. When port 8 is merged with port 9, these signals become port 8 transmit pairs for lanes 4 through 7.
PE12RP[3:0] PE12RN[3:0]	I	**PCI Express Port 12 Serial Data Receive.** Differential PCI Express receive pairs for port 12.
PE12TP[3:0] PE12TN[3:0]	O	**PCI Express Port 12 Serial Data Transmit.** Differential PCI Express transmit pairs for port 12.
PE13RP[3:0] PE13RN[3:0]	I	**PCI Express Port 13 Serial Data Receive.** Differential PCI Express receive pairs for port 13. When port 12 is merged with port 13, these signals become port 12 receive pairs for lanes 4 through 7.
PE13TP[3:0] PE13TN[3:0]	O	**PCI Express Port 13 Serial Data Transmit.** Differential PCI Express transmit pairs for port 13. When port 12 is merged with port 13, these signals become port 12 transmit pairs for lanes 4 through 7.

Table 1 PCI Express Interface Pins (Part 2 of 2)

Signal	Type	Name/Description
GCLKN[1:0] GCLKP[1:0]	I	**Global Reference Clock.** Differential reference clock input pair. This clock is used as the reference clock by on-chip PLLs to generate the clocks required for the system logic. The frequency of the differential reference clock is determined by the GCLKFSEL signal.

Table 2 Reference Clock Pins

Signal	Type	Name/Description
MSMBCLK	I/O	**Master SMBus Clock.** This bidirectional signal is used to synchronize transfers on the master SMBus.
MSMBDAT	I/O	**Master SMBus Data.** This bidirectional signal is used for data on the master SMBus.
SSMBADDR[2,1]	I	**Slave SMBus Address.** These pins determine the SMBus address to which the slave SMBus interface responds.
SSMBCLK	I/O	**Slave SMBus Clock.** This bidirectional signal is used to synchronize transfers on the slave SMBus.
SSMBDAT	I/O	**Slave SMBus Data.** This bidirectional signal is used for data on the slave SMBus.

Table 3 SMBus Interface Pins

Signal	Type	Name/Description
GPIO[0]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: PART0PERSTN Alternate function pin type: Input/Output Alternate function: Assertion of this signal initiated a partition fundamental reset in the corresponding partition.
GPIO[1]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: PART1PERSTN Alternate function pin type: Input/Output Alternate function: Assertion of this signal initiated a partition fundamental reset in the corresponding partition.
GPIO[2]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: PART2PERSTN Alternate function pin type: Input/Output Alternate function: Assertion of this signal initiated a partition fundamental reset in the corresponding partition.
GPIO[3]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: PART3PERSTN Alternate function pin type: Input/Output Alternate function: Assertion of this signal initiated a partition fundamental reset in the corresponding partition.
GPIO[4]	I	General Purpose I/O. This pin can be configured as a general purpose I/O pin. 1st Alternate function — Reserved 2nd Alternate function pin name: P0LINKUPN 2nd Alternate function pin type: Output 2nd Alternate function: Port 0 Link Up Status output.

Table 4 General Purpose I/O Pins (Part 1 of 2)

Signal	Type	Name/Description
GPIO[5]	O	General Purpose I/O. This pin can be configured as a general purpose I/O pin. 1st Alternate function pin name: GPEN 1st Alternate function pin type: Output 1st Alternate function: Hot-plug general purpose even output. 2nd Alternate function pin name: P0ACTIVEN 2nd Alternate function pin type: Output 2nd Alternate function: Port 0 Link Active Status Output.
GPIO[6]	I	General Purpose I/O. This pin can be configured as a general purpose I/O pin.
GPIO[7]	I/O	General Purpose I/O. This pin can be configured as a general purpose I/O pin.
GPIO[8]	I	General Purpose I/O. This pin can be configured as a general purpose I/O pin. Alternate function pin name: IOEXPINTN Alternate function pin type: Input Alternate function: IO expander interrupt.

Table 4 General Purpose I/O Pins (Part 2 of 2)

Signal	Type	Name/Description
CLKMODE[1:0]		**Clock Mode.** These signals determine the port clocking mode used by ports of the device.
GCLKFSEL	I	**Global Clock Frequency Select.** These signals select the frequency of the GCLKP and GCLKN signals. 0x0 100 MHz 0x1 125 MHz
P01MERGEN	I	**Port 0 and 1 Merge.** P01MERGEN is an active low signal. It is pulled low internally. When this pin is low, port 0 is merged with port 1 to form a single x8 port. The Serdes lanes associated with port 1 become lanes 4 through 7 of port 0. When this pin is high, port 0 and port 1 are not merged, and each operates as a single x4 port.
P23MERGEN	I	**Port 2 and 3 Merge.** P23MERGEN is an active low signal. It is pulled low internally. When this pin is low, port 2 is merged with port 3 to form a single x8 port. The Serdes lanes associated with port 3 become lanes 4 through 7 of port 2. When this pin is high, port 2 and port 3 are not merged, and each operates as a single x4 port.
P45MERGEN	I	**Port 4 and 5 Merge.** P45MERGEN is an active low signal. It is pulled low internally. When this pin is low, port 4 is merged with port 5 to form a single x8 port. The Serdes lanes associated with port 5 become lanes 4 through 7 of port 4. When this pin is high, port 4 and port 5 are not merged, and each operates as a single x4 port.
P67MERGEN	I	**Port 6 and 7 Merge.** P67MERGEN is an active low signal. It is pulled low internally. When this pin is low, port 6 is merged with port 7 to form a single x8 port. The Serdes lanes associated with port 7 become lanes 4 through 7 of port 6. When this pin is high, port 6 and port 7 are not merged, and each operates as a single x4 port.

Table 5 System Pins (Part 1 of 2)

Signal	Type	Name/Description
P89MERGEN	I	**Port 8 and 9 Merge.** P89MERGEN is an active low signal. It is pulled low internally. When this pin is low, port 8 is merged with port 9 to form a single x8 port. The Serdes lanes associated with port 9 become lanes 4 through 7 of port 8. When this pin is high, port 8 and port 9 are not merged, and each operates as a single x4 port.
P1213MERGEN	I	**Port 12 and 13 Merge.** P1213MERGEN is an active low signal. It is pulled low internally. When this pin is low, port 12 is merged with port13 to form a single x8 port. The Serdes lanes associated with port 13 become lanes 4 through 7 of port 12. When this pin is high, port 12 and port 13 are not merged, and each operates as a single x4 port.
PERSTN	I	**Global Reset.** Assertion of this signal resets all logic inside PES48T12G2.
RSTHALT	I	**Reset Halt.** When this signal is asserted during a PCI Express fundamental reset, PES48T12G2 executes the reset procedure and remains in a reset state with the Master and Slave SMBuses active. This allows software to read and write registers internal to the device before normal device operation begins. The device exits the reset state when the RSTHALT bit is cleared in the SWCTL register by an SMBus master.
SWMODE[3:0]	I	**Switch Mode.** These configuration pins determine the PES48T12G2 switch operating mode. **Note:** These pins should be static and not change following the negation of PERSTN. 0x0 - Normal switch mode 0x1 - Normal switch mode with Serial EEPROM initialization 0x2 through 0x7 - Reserved 0x8 - Single partition with port 0 selected as the upstream port (port 2 disabled) 0x9 - Single partition with port 2 selected as the upstream port (port 0 disabled) 0xA - Single partition with Serial EEPROM initialization and port 0 selected as the upstream port (port 2 disabled) 0xB - Single partition with Serial EEPROM initialization and port 2 selected as the upstream port (port 0 disabled) 0xE - Reserved 0xF - Reserved

Table 5 System Pins (Part 2 of 2)

Signal	Type	Name/Description
JTAG_TCK	I	**JTAG Clock**. This is an input test clock used to clock the shifting of data into or out of the boundary scan logic or JTAG Controller. JTAG_TCK is independent of the system clock with a nominal 50% duty cycle.
JTAG_TDI	I	**JTAG Data Input**. This is the serial data input to the boundary scan logic or JTAG Controller.

Table 6 Test Pins (Part 1 of 2)

Signal	Type	Name/Description
JTAG_TDO	O	**JTAG Data Output**. This is the serial data shifted out from the boundary scan logic or JTAG Controller. When no data is being shifted out, this signal is tri-stated.
JTAG_TMS	I	**JTAG Mode**. The value on this signal controls the test mode select of the boundary scan logic or JTAG Controller.
JTAG_TRST_N	I	**JTAG Reset**. This active low signal asynchronously resets the boundary scan logic and JTAG TAP Controller. An external pull-up on the board is recommended to meet the JTAG specification in cases where the tester can access this signal. However, for systems running in functional mode, one of the following should occur: 1) actively drive this signal low with control logic 2) statically drive this signal low with an external pull-down on the board

Table 6 Test Pins (Part 2 of 2)

Signal	Type	Name/Description
REFRES[13,12,9:0]	I/O	**External Reference Resistors.** Provides a reference for the SerDes bias currents and PLL calibration circuitry. A 3 kOhm +/- 1% resistor should be connected from these pins to ground.
REFRESPLL	I/O	**PLL External Reference Resistor.** Provides a reference for the PLL bias currents and PLL calibration circuitry. A 3K Ohm +/- 1% resistor should be connected from this pin to ground.
V_{DD}CORE	I	**Core V_{DD}.** Power supply for core logic (1.0V).
V_{DD}I/O	I	**I/O V_{DD}.** LVTTL I/O buffer power supply (2.5V or preferred 3.3V).
V_{DD}PEA	I	**PCI Express Analog Power.** Serdes analog power supply (1.0V).
V_{DD}PEHA	I	**PCI Express Analog High Power.** Serdes analog power supply (2.5V).
V_{DD}PETA	I	**PCI Express Transmitter Analog Voltage.** Serdes transmitter analog power supply (1.0V).
V_{SS}	I	**Ground.**

Table 7 Power, Ground, and SerDes Resistor Pins

Pin Characteristics

Note: Some input pads of the switch do not contain internal pull-ups or pull-downs. Unused SMBus and System inputs should be tied off to appropriate levels. This is especially critical for unused control signal inputs which, if left floating, could adversely affect operation. Also, any of these pins left floating can cause a slight increase in power consumption. Finally, unused Serdes (Rx and Tx) pins should be left floating.

Function	Pin Name	Type	Buffer	I/O Type	Internal Resistor[1]	Notes
PCI Express Interface	PE00RN[3:0]	I	PCIe Differential[2]	Serial Link		
	PE00RP[3:0]	I				
	PE00TN[3:0]	O				
	PE00TP[3:0]	O				
	PE01RN[3:0]	I				
	PE01RP[3:0]	I				
	PE01TN[3:0]	O				
	PE01TP[3:0]	O				
	PE02RN[3:0]	I				
	PE02RP[3:0]	I				
	PE02TN[3:0]	O				
	PE02TP[3:0]	O				
	PE03RN[3:0]	I				
	PE03RP[3:0]	I				
	PE03TN[3:0]	O				
	PE03TP[3:0]	O				
	PE04RN[3:0]	I				
	PE04RP[3:0]	I				
	PE04TN[3:0]	O				
	PE04TP[3:0]	O				
	PE05RN[3:0]	I				
	PE05RP[3:0]	I				
	PE05TN[3:0]	O				
	PE05TP[3:0]	O				
	PE06RN[3:0]	I				
	PE06RP[3:0]	I				
	PE06TN[3:0]	O				
	PE06TP[3:0]	O				
	PE07RN[3:0]	I				
	PE07RP[3:0]	I				
	PE07TN[3:0]	O				
	PE07TP[3:0]	O				
	PE08RN[3:0]	I				
	PE08RP[3:0]	I				
	PE08TN[3:0]	O				

Table 8 Pin Characteristics (Part 1 of 3)

Function	Pin Name	Type	Buffer	I/O Type	Internal Resistor[1]	Notes
PCI Express Interface (Cont.)	PE08TP[3:0]	O	PCIe Differential	Serial Link		
	PE09RN[3:0]	I				
	PE09RP[3:0]	I				
	PE09TN[3:0]	O				
	PE09TP[3:0]	O				
	PE12RN[3:0]	I				
	PE12RP[3:0]	I				
	PE12TN[3:0]	O				
	PE12TP[3:0]	O				
	PE13RN[3:0]	I				
	PE13RP[3:0]	I				
	PE13TN[3:0]	O				
	PE13TP[3:0]	O				
	GCLKN[1:0]	I	HCSL	Diff. Clock Input		Refer to Table 9
	GCLKP[1:0]	I				
SMBus	MSMBCLK	I/O	LVTTL	STI[3]		pull-up on board
	MSMBDAT	I/O		STI		pull-up on board
	SSMBADDR[2:1]	I		Input	pull-up	
	SSMBCLK	I/O		STI		pull-up on board
	SSMBDAT	I/O		STI		pull-up on board
General Purpose I/O	GPIO[8:0]	I/O	LVTTL	STI, High Drive	pull-up	
System Pins	CLKMODE[1:0]	I	LVTTL	Input	pull-up	
	GCLKFSEL	I			pull-down	
	P01MERGEN	I			pull-down	
	P23MERGEN	I			pull-down	
	P45MERGEN	I			pull-down	
	P67MERGEN	I			pull-down	
	P89MERGEN	I			pull-down	
	P1213MERGEN	I			pull-down	
	PERSTN	I		STI		
	RSTHALT	I		Input	pull-down	
	SWMODE[3:0]	I			pull-down	
EJTAG / JTAG	JTAG_TCK	I	LVTTL	STI	pull-up	
	JTAG_TDI	I		STI	pull-up	
	JTAG_TDO	O				
	JTAG_TMS	I		STI	pull-up	
	JTAG_TRST_N	I		STI	pull-up	

Table 8 Pin Characteristics (Part 2 of 3)

Function	Pin Name	Type	Buffer	I/O Type	Internal Resistor[1]	Notes
SerDes Reference Resistors	REFRES00	I/O	Analog			
	REFRES01	I/O				
	REFRES02	I/O				
	REFRES03	I/O				
	REFRES04	I/O				
	REFRES05	I/O				
	REFRES06	I/O				
	REFRES07	I/O				
	REFRES08	I/O				
	REFRES09	I/O				
	REFRES12	I/O				
	REFRES13	I/O				
	REFRESPLL	I/O				

Table 8 Pin Characteristics (Part 3 of 3)

1. Internal resistor values under typical operating conditions are 92K Ω for pull-up and 91K Ω for pull-down.

2. All receiver pins set the DC common mode voltage to ground. All transmitters must be AC coupled to the media.

3. Schmitt Trigger Input (STI).

Logic Diagram — PES48T12G2

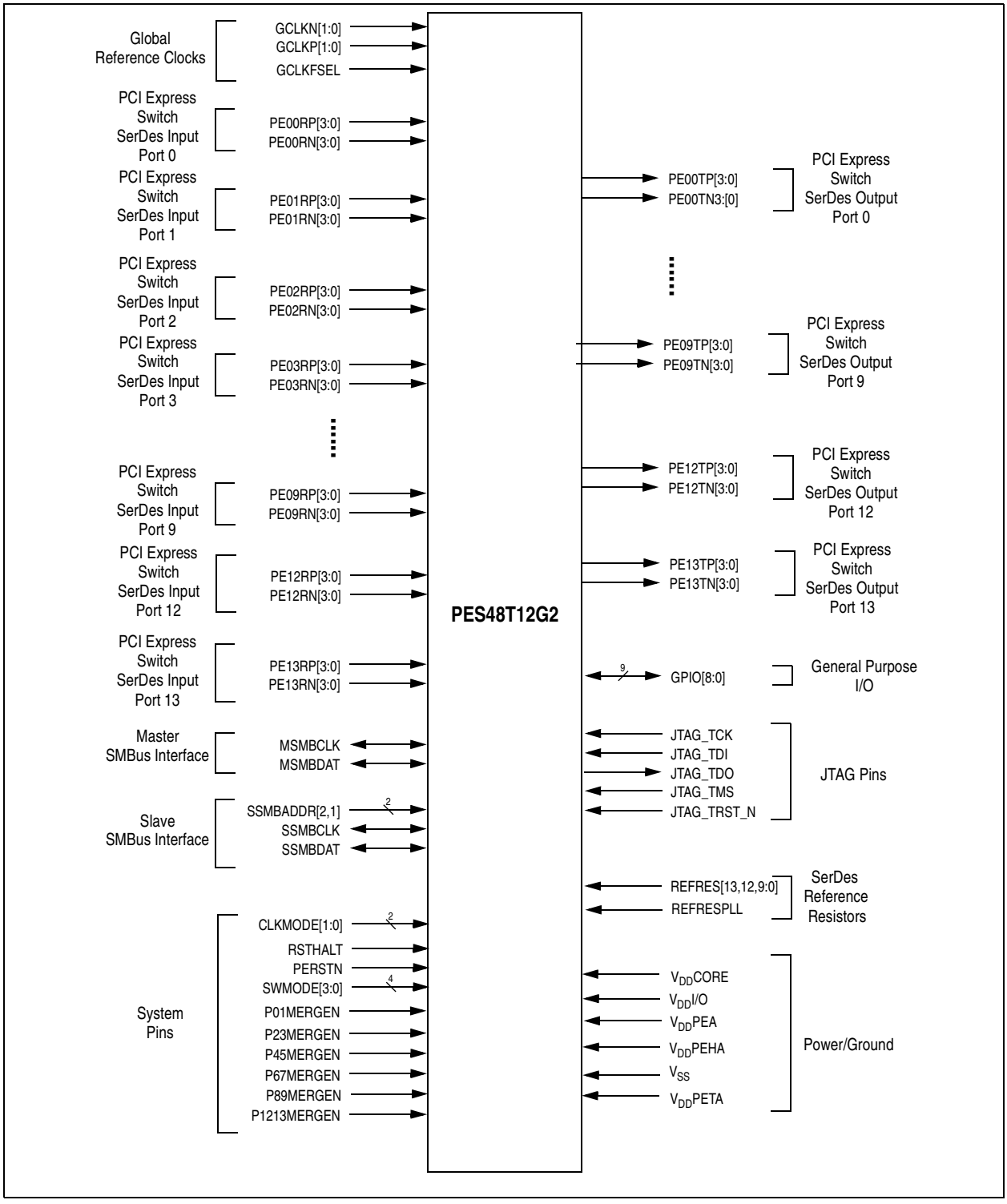


Figure 3 PES48T12G2 Logic Diagram

System Clock Parameters

Values based on systems running at recommended supply voltages and operating temperatures, as shown in Tables 13 and 14.

Parameter	Description	Condition	Min	Typical	Max	Unit
$Refclk_{FREQ}$	Input reference clock frequency range		100		125[1]	MHz
T_{C-RISE}	Rising edge rate	Differential	0.6		4	V/ns
T_{C-FALL}	Falling edge rate	Differential	0.6		4	V/ns
V_{IH}	Differential input high voltage	Differential	+150			mV
V_{IL}	Differential input low voltage	Differential			-150	mV
V_{CROSS}	Absolute single-ended crossing point voltage	Single-ended	+250		+550	mV
$V_{CROSS-DELTA}$	Variation of V_{CROSS} over all rising clock edges	Single-ended			+140	mV
V_{RB}	Ring back voltage margin	Differential	-100		+100	mV
T_{STABLE}	Time before V_{RB} is allowed	Differential	500			ps
$T_{PERIOD-AVG}$	Average clock period accuracy		-300		2800	ppm
$T_{PERIOD-ABS}$	Absolute period, including spread-spectrum and jitter		9.847		10.203	ns
$T_{CC-JITTER}$	Cycle to cycle jitter				150	ps
V_{MAX}	Absolute maximum input voltage				+1.15	V
V_{MIN}	Absolute minimum input voltage		-0.3			V
Duty Cycle	Duty cycle		40		60	%
Rise/Fall Matching	Single ended rising Refclk edge rate versus falling Refclk edge rate			20		%
Z_{C-DC}	Clock source output DC impedance		40		60	Ω

Table 9 Input Clock Requirements

1. The input clock frequency will be either 100 or 125 MHz depending on signal GCLKFSEL.

AC Timing Characteristics

Parameter	Description	Gen 1			Gen 2			Units
		Min[1]	Typ[1]	Max[1]	Min[1]	Typ[1]	Max[1]	
PCIe Transmit								
UI	Unit Interval	399.88	400	400.12	199.94	200	200.06	ps
T_{TX-EYE}	Minimum Tx Eye Width	0.75			0.75			UI
$T_{TX-EYE-MEDIAN-to-MAX-JITTER}$	Maximum time between the jitter median and maximum deviation from the median			0.125				UI
$T_{TX-RISE}$, $T_{TX-FALL}$	TX Rise/Fall Time: 20% - 80%	0.125			0.15			UI
$T_{TX-IDLE-MIN}$	Minimum time in idle	20			20			UI

Table 10 PCIe AC Timing Characteristics (Part 1 of 2)

Parameter	Description	Gen 1			Gen 2			Units
		Min[1]	Typ[1]	Max[1]	Min[1]	Typ[1]	Max[1]	
$T_{TX-IDLE-SET-TO-IDLE}$	Maximum time to transition to a valid Idle after sending an Idle ordered set			8			8	ns
$T_{TX-IDLE-TO-DIFF-DATA}$	Maximum time to transition from valid idle to diff data			8			8	ns
$T_{TX-SKEW}$	Transmitter data skew between any 2 lanes			1.3			1.3	ns
$T_{MIN-PULSED}$	Minimum Instantaneous Lone Pulse Width	NA			0.9			UI
$T_{TX-HF-DJ-DD}$	Transmitter Deterministic Jitter > 1.5MHz Bandwidth	NA					0.15	UI
$T_{RF-MISMATCH}$	Rise/Fall Time Differential Mismatch	NA					0.1	UI
PCIe Receive								
UI	Unit Interval	399.88	400	400.12	199.94		200.06	ps
$T_{RX-EYE\ (with\ jitter)}$	Minimum Receiver Eye Width (jitter tolerance)	0.4			0.4			UI
$T_{RX-EYE-MEDIUM\ TO\ MAX\ JITTER}$	Max time between jitter median & max deviation			0.3				UI
$T_{RX-SKEW}$	Lane to lane input skew			20			8	ns
$T_{RX-HF-RMS}$	1.5 — 100 MHz RMS jitter (common clock)	NA					3.4	ps
$T_{RX-HF-DJ-DD}$	Maximum tolerable DJ by the receiver (common clock)	NA					88	ps
$T_{RX-LF-RMS}$	10 KHz to 1.5 MHz RMS jitter (common clock)	NA					4.2	ps
$T_{RX-MIN-PULSE}$	Minimum receiver instantaneous eye width	NA			0.6			UI

Table 10 PCIe AC Timing Characteristics (Part 2 of 2)

1. Minimum, Typical, and Maximum values meet the requirements under PCI Specification 2.0

Signal	Symbol	Reference Edge	Min	Max	Unit	Timing Diagram Reference
GPIO						
GPIO[8:0][1]	Tpw[2]	None	50	—	ns	

Table 11 GPIO AC Timing Characteristics

1. GPIO signals must meet the setup and hold times if they are synchronous or the minimum pulse width if they are asynchronous.

2. The values for this symbol were determined by calculation, not by testing.

Signal	Symbol	Reference Edge	Min	Max	Unit	Timing Diagram Reference
JTAG						
JTAG_TCK	Tper_16a	none	50.0	—	ns	See Figure 4.
	Thigh_16a, Tlow_16a		10.0	25.0	ns	
JTAG_TMS[1], JTAG_TDI	Tsu_16b	JTAG_TCK rising	2.4	—	ns	
	Thld_16b		1.0	—	ns	
JTAG_TDO	Tdo_16c	JTAG_TCK falling	—	20	ns	
	Tdz_16c[2]		—	20	ns	
JTAG_TRST_N	Tpw_16d[2]	none	25.0	—	ns	

Table 12 JTAG AC Timing Characteristics

1. The JTAG specification, IEEE 1149.1, recommends that JTAG_TMS should be held at 1 while the signal applied at JTAG_TRST_N changes from 0 to 1. Otherwise, a race may occur if JTAG_TRST_N is deasserted (going from low to high) on a rising edge of JTAG_TCK when JTAG_TMS is low, because the TAP controller might go to either the Run-Test/Idle state or stay in the Test-Logic-Reset state.

2. The values for this symbol were determined by calculation, not by testing.

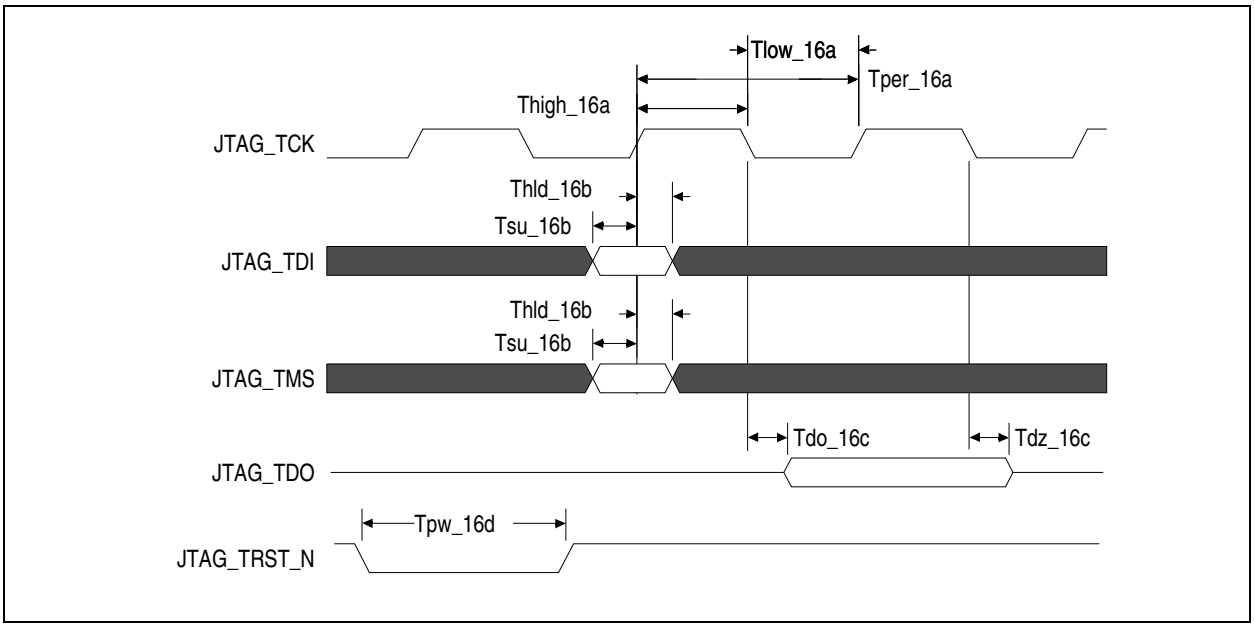


Figure 4 JTAG AC Timing Waveform

Recommended Operating Supply Voltages

Symbol	Parameter	Minimum	Typical	Maximum	Unit
V_{DD}CORE	Internal logic supply	0.9	1.0	1.1	V
V_{DD}I/O	I/O supply except for SerDes	2.25	2.5	2.75	V
		3.125	3.3	3.465	V
V_{DD}PEA[1]	PCI Express Analog Power	0.95	1.0	1.1	V
V_{DD}PEHA[2]	PCI Express Analog High Power	2.25	2.5	2.75	V
V_{DD}PETA[1]	PCI Express Transmitter Analog Voltage	0.95	1.0	1.1	V
V_{SS}	Common ground	0	0	0	V

Table 13 PES48T12G2 Operating Voltages

1. V_{DD}PEA and V_{DD}PETA should have no more than 25m$V_{peak-peak}$ AC power supply noise superimposed on the 1.0V nominal DC value.
2. V_{DD}PEHA should have no more than 50m$V_{peak-peak}$ AC power supply noise superimposed on the 2.5V nominal DC value.

Power-Up/Power-Down Sequence

During power supply ramp-up, V_{DD}CORE must remain at least 1.0V below V_{DD}I/O at all times. There are no other power-up sequence requirements for the various operating supply voltages.

The power-down sequence can occur in any order.

Recommended Operating Temperature

Grade	Temperature
Commercial	0°C to +70°C Ambient
Industrial	-40°C to +85°C Ambient

Table 14 PES48T12G2 Operating Temperatures

Power Consumption

Typical power is measured under the following conditions: 25°C Ambient, 35% total link usage on all ports, typical voltages defined in Table 13 (and also listed below).

Maximum power is measured under the following conditions: 70°C Ambient, 85% total link usage on all ports, maximum voltages defined in Table 13 (and also listed below).

Number of Active Lanes per Port		Core Supply		PCIe Analog Supply		PCIe Analog High Supply		PCIe Transmitter Supply		I/O Supply		Total	
		Typ 1.0V	Max 1.1V	Typ 1.0V	Max 1.1V	Typ 2.5V	Max 2.75V	Typ 1.0V	Max 1.1V	Typ 2.5V	Max 2.75V	Typ Power	Max Power
8/8/8/8/8/8 (Full Swing)	mA	3200	5336	2313	2705	816	825	845	898	24	29		
	Watts	3.20	5.87	2.31	2.98	2.04	2.27	0.85	0.99	0.06	0.08	8.46	12.18
8/8/8/8/8/8 (Half Swing)	mA	3200	5336	1989	2327	816	825	439	467	24	29		
	Watts	3.20	5.87	1.99	2.56	2.04	2.27	0.44	0.51	0.06	0.08	7.73	11.29

Table 15 PES48T12G2 Power Consumption — 2.5V I/O

Number of Active Lanes per Port		Core Supply		PCIe Analog Supply		PCIe Analog High Supply		PCIe Transmitter Supply		I/O Supply		Total	
		Typ 1.0V	Max 1.1V	Typ 1.0V	Max 1.1V	Typ 2.5V	Max 2.75V	Typ 1.0V	Max 1.1V	Typ 3.3V	Max 3.465V	Typ Power	Max Power
8/8/8/8/8/8 (Full Swing)	mA	3200	5336	2313	2705	816	825	845	898	30	35		
	Watts	3.20	5.87	2.31	2.98	2.04	2.27	0.85	0.99	0.10	0.12	8.50	12.22
8/8/8/8/8/8 (Half Swing)	mA	3200	5336	1989	2327	816	825	439	467	30	35		
	Watts	3.20	5.87	1.99	2.56	2.04	2.27	0.44	0.51	0.10	0.12	7.77	11.33

Table 16 PES48T12G2 Power Consumption — 3.3V I/O

Note 1: I/O supply of 3.3V is preferred.

Note 2: The above power consumption assumes that all ports are functioning at Gen2 (5.0 GT/S) speeds. Power consumption can be reduced by turning off unused ports through software or through boot EEPROM. Power savings will occur in V_{DD}PEA, V_{DD}PEHA, and V_{DD}PETA. Power savings can be estimated as directly proportional to the number of unused ports, since the power consumption of a turned-off port is close to zero. For example, if 2 ports out of 12 are turned off, then the power savings for each of the above three power rails can be calculated quite simply as 2/12 multiplied by the power consumption indicated in the above table.

Note 3: Using a port in Gen1 mode (2.5GT/S) results in approximately 18% power savings for each power rail: V_{DD}PEA, V_{DD}PEHA, and V_{DD}PETA.

Thermal Considerations

This section describes thermal considerations for the PES48T12G2 (27mm^2 FCBGA676 package). The data in Table 17 below contains information that is relevant to the thermal performance of the PES48T12G2 switch.

Symbol	Parameter	Value	Units	Conditions
$T_{J(max)}$	Junction Temperature	125	^{o}C	Maximum
$T_{A(max)}$	Ambient Temperature	70	^{o}C	Maximum for commercial-rated products
		85	^{o}C	Maximum for industrial-rated products
$\theta_{JA(effective)}$	Effective Thermal Resistance, Junction-to-Ambient	14.6	^{o}C/W	Zero air flow
		7.8	^{o}C/W	1 m/S air flow
		6.4	^{o}C/W	2 m/S air flow
θ_{JB}	Thermal Resistance, Junction-to-Board	2.7	^{o}C/W	
θ_{JC}	Thermal Resistance, Junction-to-Case	0.15	^{o}C/W	
P	Power Dissipation of the Device	12.22	Watts	Maximum

Table 17 Thermal Specifications for PES48T12G2, 27x27 mm FCBGA676 Package

Note: It is important for the reliability of this device in any user environment that the junction temperature not exceed the $T_{J(max)}$ value specified in Table 17. Consequently, the effective junction to ambient thermal resistance (θ_{JA}) for the worst case scenario must be maintained below the value determined by the formula:

$$\theta_{JA} = (T_{J(max)} - T_{A(max)})/P$$

Given that the values of $T_{J(max)}$, $T_{A(max)}$, and P are known, the value of desired θ_{JA} becomes a known entity to the system designer. How to achieve the desired θ_{JA} is left up to the board or system designer, but in general, it can be achieved by adding the effects of θ_{JC} (value provided in Table 17), thermal resistance of the chosen adhesive (θ_{CS}), that of the heat sink (θ_{SA}), amount of airflow, and properties of the circuit board (number of layers and size of the board). It is strongly recommended that users perform their own thermal analysis for their own board and system design scenarios.

DC Electrical Characteristics

Values based on systems running at recommended supply voltages, as shown in Table 13.

Note: See Table 8, Pin Characteristics, for a complete I/O listing.

I/O Type	Parameter	Description	Gen1			Gen2			Unit	Conditions
			Min[1]	Typ[1]	Max[1]	Min[1]	Typ[1]	Max[1]		
Serial Link	PCIe Transmit									
	$V_{TX-DIFFp-p}$	Differential peak-to-peak output voltage	800		1200	800		1200	mV	
	$V_{TX-DIFFp-p-LOW}$	Low-Drive Differential Peak to Peak Output Voltage	400		1200	400		1200	mV	
	$V_{TX-DE-RATIO-3.5dB}$	De-emphasized differential output voltage	-3		-4	-3.0	-3.5	-4.0	dB	
	$V_{TX-DE-RATIO-6.0dB}$	De-emphasized differential output voltage	NA			-5.5	-6.0	-6.5	dB	
	$V_{TX-DC-CM}$	DC Common mode voltage	0		3.6	0		3.6	V	
	$V_{TX-CM-ACP}$	RMS AC peak common mode output voltage			20				mV	
	$V_{TX-CM-DC-active-idle-delta}$	Abs delta of DC common mode voltage between L0 and idle			100			100	mV	
	$V_{TX-CM-DC-line-delta}$	Abs delta of DC common mode voltage between D+ and D-			25			25	mV	
	$V_{TX-Idle-DiffP}$	Electrical idle diff peak output			20			20	mV	
	$RL_{TX-DIFF}$	Transmitter Differential Return loss	10					10	dB	0.05 - 1.25GHz
								8	dB	1.25 - 2.5GHz
	RL_{TX-CM}	Transmitter Common Mode Return loss	6					6	dB	
	$Z_{TX-DIFF-DC}$	DC Differential TX impedance	80	100	120			120	Ω	
	VTX-CM-ACpp	Peak-Peak AC Common	NA					100	mV	
	$V_{TX-DC-CM}$	Transmit Driver DC Common Mode Voltage	0		3.6	0		3.6	V	
	$V_{TX-RCV-DETECT}$	The amount of voltage change allowed during Receiver Detection			600			600	mV	
	$I_{TX-SHORT}$	Transmitter Short Circuit Current Limit	0		90				90	mA

Table 18 DC Electrical Characteristics (Part 1 of 2)

I/O Type	Parameter	Description	Gen1			Gen2			Unit	Conditions
			Min[1]	Typ[1]	Max[1]	Min[1]	Typ[1]	Max[1]		
Serial Link (cont.)	PCIe Receive									
	$V_{RX-DIFFp-p}$	Differential input voltage (peak-to-peak)	175		1200	120		1200	mV	
	$RL_{RX-DIFF}$	Receiver Differential Return Loss	10					10	dB	0.05 - 1.25GHz
								8		1.25 - 2.5GHz
	RL_{RX-CM}	Receiver Common Mode Return Loss	6					6	dB	
	$Z_{RX-DIFF-DC}$	Differential input impedance (DC)	80	100	120	Refer to return loss spec			Ω	
	Z_{RX--DC}	DC common mode impedance	40	50	60	40		60	Ω	
	$Z_{RX-COMM-DC}$	Powered down input common mode impedance (DC)	200k	350k				50k	Ω	
	$Z_{RX-HIGH-IMP-DC-POS}$	DC input CM input impedance for V>0 during reset or power down			50k			50k	Ω	
	$Z_{RX-HIGH-IMP-DC-NEG}$	DC input CM input impedance for V<0 during reset or power down			1.0k			1.0k	Ω	
	$V_{RX-IDLE-DET-DIFFp-p}$	Electrical idle detect threshold	65		175	65		175	mV	
	$V_{RX-CM-ACp}$	Receiver AC common-mode peak voltage			150			150	mV	$V_{RX-CM-ACp}$
PCIe REFCLK										
	C_{IN}	Input Capacitance	1.5	—		1.5	—		pF	
Other I/Os										
LOW Drive Output	I_{OL}		—	2.5	—	—	2.5	—	mA	V_{OL} = 0.4v
	I_{OH}		—	-5.5	—	—	-5.5	—	mA	V_{OH} = 1.5V
High Drive Output	I_{OL}		—	12.0	—	—	12.0	—	mA	V_{OL} = 0.4v
	I_{OH}		—	-20.0	—	—	-20.0	—	mA	V_{OH} = 1.5V
Schmitt Trigger Input (STI)	V_{IL}		-0.3	—	0.8	-0.3	—	0.8	V	—
	V_{IH}		2.0	—	V_{DD}I/O + 0.5	2.0	—	V_{DD}I/O + 0.5	V	—
Input	V_{IL}		-0.3	—	0.8	-0.3	—	0.8	V	—
	V_{IH}		2.0	—	V_{DD}I/O + 0.5	2.0	—	V_{DD}I/O + 0.5	V	—
Capacitance	C_{IN}		—	—	8.5	—	—	8.5	pF	—
Leakage	Inputs		—	—	± 10	—	—	± 10	µA	V_{DD}I/O (max)
	$I/O_{LEAK\ W/O}$ Pull-ups/downs		—	—	± 10	—	—	± 10	µA	V_{DD}I/O (max)
	$I/O_{LEAK\ WITH}$ Pull-ups/downs		—	—	± 80	—	—	± 80	µA	V_{DD}I/O (max)

Table 18 DC Electrical Characteristics (Part 2 of 2)

1. Minimum, Typical, and Maximum values meet the requirements under PCI Specification 2.0.

Absolute Maximum Voltage Rating

Core Supply	PCIe Analog Supply	PCIe Analog High Supply	PCIe Transmitter Supply	I/O Supply
1.5V	1.5V	4.6V	1.5V	4.6V

Table 19 PES48T12G2 Absolute Maximum Voltage Rating

Warning: For proper and reliable operation in adherence with this data sheet, the device should not exceed the recommended operating voltages in Table 13. The absolute maximum operating voltages in Table 19 are offered to provide guidelines for voltage excursions outside the recommended voltage ranges. Device functionality is not guaranteed at these conditions and sustained operation at these values or any exposure to voltages outside the maximum range may adversely affect device functionality and reliability.

SMBus Characterization

Symbol	Parameter	SMBus 2.0 Char. Data[1]			Unit
		3V	3.3V	3.6V	
DC Parameter for SDA Pin					
V_{IL}	Input Low	1.16	1.26	1.35	V
V_{IH}	Input High	1.56	1.67	1.78	V
$V_{OL@350uA}$	Output Low	15	15	15	mV
$I_{OL@0.4V}$		23	24	25	mA
I_{Pullup}	Current Source	—	—	—	µA
I_{IL_Leak}	Input Low Leakage	0	0	0	µA
I_{IH_Leak}	Input High Leakage	0	0	0	µA
DC Parameter for SCL Pin					
$V_{IL\ (V)}$	Input Low	1.11	1.2	1.31	V
$V_{IH\ (V)}$	Input High	1.54	1.65	1.76	V
I_{IL_Leak}	Input Low Leakage	0	0	0	µA
I_{IH_Leak}	Input High Leakage	0	0	0	µA

Table 20 SMBus DC Characterization Data

1. Data at room and hot temperature.

Symbol	Parameter	SMBus @3.3V ±10%[1]		Unit
		Min	Max	
F_{SCL}	Clock frequency	5	600	KHz
T_{BUF}	Bus free time between Stop and Start	3.5	—	µs
$T_{HD:STA}$	Start condition hold time	1	—	µs
$T_{SU:STA}$	Start condition setup time	1	—	µs
$T_{SU:STO}$	Stop condition setup time	1	—	µs
$T_{HD:DAT}$	Data hold time	1	—	ns
$T_{SU:DAT}$	Data setup time	1	—	ns
$T_{TIMEOUT}$	Detect clock low time out	—	74.7	ms
T_{LOW}	Clock low period	3.7	—	µs
T_{HIGH}	Clock high period	3.7	—	µs
T_F	Clock/Data fall time	—	72.2	ns
T_R	Clock/Data rise time	—	68.3	ns
$T_{POR@10kHz}$	Time which a device must be operational after power-on reset	20	—	ms

Table 21 SMBus AC Timing Data

1. Data at room and hot temperature.

PES48T12G2 Package Pinout, 27x27mm 676-BGA Signal Pinout

The following table lists the pin numbers and signal names for the PES48T12G2 (27x27mm) device.

Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt
A1	V_{SS}		B9	PE08TN0		C17	V_{SS}		D25	V_{DD}I/O	
A2	V_{SS}		B10	V_{SS}		C18	V_{SS}		D26	V_{DD}I/O	
A3	V_{DD}I/O		B11	PE03TN3		C19	V_{SS}		E1	V_{SS}	
A4	V_{SS}		B12	PE03TN2		C20	V_{SS}		E2	V_{SS}	
A5	PE08TP3		B13	V_{SS}		C21	V_{SS}		E3	V_{SS}	
A6	PE08TP2		B14	PE03TN1		C22	V_{SS}		E4	V_{SS}	
A7	V_{SS}		B15	PE03TN0		C23	JTAG_TDO		E5	PE08RP3	
A8	PE08TP1		B16	V_{SS}		C24	JTAG_TDI		E6	PE08RP2	
A9	PE08TP0		B17	PE02TN3		C25	SSMBCLK		E7	V_{SS}	
A10	V_{SS}		B18	PE02TN2		C26	SSMBADDR1		E8	PE08RP1	
A11	PE03TP3		B19	V_{SS}		D1	V_{DD}I/O		E9	PE08RP0	
A12	PE03TP2		B20	PE02TN1		D2	V_{DD}I/O		E10	V_{SS}	
A13	V_{SS}		B21	PE02TN0		D3	V_{SS}		E11	PE03RP3	
A14	PE03TP1		B22	V_{DD}I/O		D4	V_{SS}		E12	PE03RP2	
A15	PE03TP0		B23	MSMBCLK		D5	PE08RN3		E13	V_{SS}	
A16	V_{SS}		B24	PERSTN		D6	PE08RN2		E14	PE03RP1	
A17	PE02TP3		B25	SSMBDAT		D7	V_{SS}		E15	PE03RP0	
A18	PE02TP2		B26	SSMBADDR2		D8	PE08RN1		E16	V_{SS}	
A19	V_{SS}		C1	V_{SS}		D9	PE08RN0		E17	PE02RP3	
A20	PE02TP1		C2	V_{SS}		D10	V_{SS}		E18	PE02RP2	
A21	PE02TP0		C3	V_{SS}		D11	PE03RN3		E19	V_{SS}	
A22	V_{DD}I/O		C4	V_{SS}		D12	PE03RN2		E20	PE02RP1	
A23	MSMBDAT		C5	V_{SS}		D13	REFRES03		E21	PE02RP0	
A24	JTAG_TMS		C6	V_{SS}		D14	PE03RN1		E22	PE01RP3	
A25	CLKMODE1		C7	V_{SS}		D15	PE03RN0		E23	PE01RN3	
A26	JTAG_TCK		C8	V_{SS}		D16	V_{SS}		E24	V_{SS}	
B1	V_{SS}		C9	V_{SS}		D17	PE02RN3		E25	PE01TN3	
B2	V_{SS}		C10	V_{SS}		D18	PE02RN2		E26	PE01TP3	
B3	V_{DD}I/O		C11	V_{SS}		D19	V_{SS}		F1	PE09TP0	
B4	V_{SS}		C12	V_{SS}		D20	PE02RN1		F2	PE09TN0	
B5	PE08TN3		C13	V_{SS}		D21	PE02RN0		F3	V_{SS}	
B6	PE08TN2		C14	V_{SS}		D22	JTAG_TRST_N		F4	PE09RN0	
B7	V_{SS}		C15	V_{SS}		D23	V_{SS}		F5	PE09RP0	
B8	PE08TN1		C16	V_{SS}		D24	V_{SS}		F6	V_{SS}	

Table 22 PES48T12G2 Signal Pin-Out (Part 1 of 5)

Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt
F7	V_{SS}		G18	V_{DD}PETA		J3	V_{SS}		K14	V_{SS}	
F8	V_{DD}PEHA		G19	V_{DD}PEHA		J4	PE09RN2		K15	V_{DD}CORE	
F9	REFRES08		G20	V_{SS}		J5	PE09RP2		K16	V_{DD}CORE	
F10	V_{DD}PEHA		G21	V_{SS}		J6	V_{DD}PEA		K17	V_{SS}	
F11	V_{DD}PETA		G22	V_{SS}		J7	V_{DD}PEA		K18	V_{SS}	
F12	REFRESPLL		G23	V_{SS}		J8	V_{DD}PEA		K19	V_{DD}PETA	
F13	GCLKP0		G24	V_{SS}		J9	V_{SS}		K20	V_{DD}PETA	
F14	V_{DD}PEA		G25	V_{SS}		J10	V_{SS}		K21	V_{DD}PETA	
F15	V_{SS}		G26	V_{SS}		J11	V_{DD}CORE		K22	V_{SS}	
F16	REFRES02		H1	V_{SS}		J12	V_{DD}CORE		K23	V_{SS}	
F17	V_{DD}PEA		H2	V_{SS}		J13	V_{SS}		K24	V_{SS}	
F18	V_{DD}PETA		H3	V_{SS}		J14	V_{SS}		K25	V_{SS}	
F19	V_{DD}PEHA		H4	V_{SS}		J15	V_{DD}CORE		K26	V_{SS}	
F20	V_{SS}		H5	V_{SS}		J16	V_{DD}CORE		L1	V_{SS}	
F21	V_{SS}		H6	V_{DD}PEA		J17	V_{SS}		L2	V_{SS}	
F22	PE01RP2		H7	V_{DD}PEA		J18	V_{SS}		L3	V_{SS}	
F23	PE01RN2		H8	V_{DD}PEA		J19	V_{DD}PEA		L4	V_{SS}	
F24	V_{SS}		H9	V_{SS}		J20	V_{DD}PEA		L5	V_{SS}	
F25	PE01TN2		H10	V_{SS}		J21	V_{DD}PEA		L6	V_{DD}PEHA	
F26	PE01TP2		H11	V_{DD}CORE		J22	PE01RP0		L7	V_{DD}PEHA	
G1	PE09TP1		H12	V_{DD}CORE		J23	PE01RN0		L8	V_{DD}PEHA	
G2	PE09TN1		H13	V_{SS}		J24	V_{SS}		L9	V_{SS}	
G3	V_{SS}		H14	V_{SS}		J25	PE01TN0		L10	V_{SS}	
G4	PE09RN1		H15	V_{DD}CORE		J26	PE01TP0		L11	V_{DD}CORE	
G5	PE09RP1		H16	V_{DD}CORE		K1	PE09TP3		L12	V_{DD}CORE	
G6	V_{SS}		H17	V_{SS}		K2	PE09TN3		L13	V_{SS}	
G7	V_{SS}		H18	V_{SS}		K3	V_{SS}		L14	V_{SS}	
G8	V_{DD}PEHA		H19	V_{DD}PEA		K4	PE09RN3		L15	V_{DD}CORE	
G9	REFRES09		H20	V_{DD}PEA		K5	PE09RP3		L16	V_{DD}CORE	
G10	V_{DD}PEHA		H21	V_{DD}PEA		K6	V_{DD}PETA		L17	V_{SS}	
G11	V_{DD}PETA		H22	PE01RP1		K7	V_{DD}PETA		L18	V_{SS}	
G12	V_{SS}		H23	PE01RN1		K8	V_{DD}PETA		L19	V_{DD}PEHA	
G13	GCLKN0		H24	V_{SS}		K9	V_{SS}		L20	REFRES01	
G14	V_{DD}PEA		H25	PE01TN1		K10	V_{SS}		L21	V_{DD}PETA	
G15	V_{SS}		H26	PE01TP1		K11	V_{DD}CORE		L22	PE00RP3	
G16	NC		J1	PE09TP2		K12	V_{DD}CORE		L23	PE00RN3	
G17	V_{DD}PEA		J2	PE09TN2		K13	V_{SS}		L24	V_{SS}	

Table 22 PES48T12G2 Signal Pin-Out (Part 2 of 5)